



OLED SPECIFICATION

Model No:

REX012864UWPP3N00000

CUSTOMER:

APPROVED BY	
PCB VERSION	
DATE	

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1. Revision History

VERSION	DATE	REVISED PAGE NO.	Note
0	2018/07/06		First release
Α	2018/10/30		Modify VSL pin of the
			3.1 Application
			recommendations.
			Add 6.3 Application
			Note for RAM
			mapping
В	2018/11/27		Modify Static
			electricity test
_			Content of Test
С	2019/07/11		Modify Application
_			recommendations
D	2019/09/02		Modify Precautions in
_			use of OLED Modules
E	2019/10/04		Add 6.4 Command
			Table



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- 1.General Specification
- 2. Module Classification Information
- 3.Interface Pin Function
- 4. Contour Drawing & Block Diagram
- 5. Absolute Maximum Ratings
- 6. Electrical Characteristics
- 7. Optical Characteristics
- 8.OLED Lifetime
- 9.Reliability
- 10.Inspection specification
- 11.Precautions in use of OLED Modules



1.General Specification

The Features is described as follow:

■ Dot Matrix: 128 x 64

■ Module dimension: 73.0 x 41.86 x 2.01 mm

Active Area: 61.41 x 30.69 mm

■ Pixel Size: 0.45 x 0.45 mm

■ Pixel Pitch: 0.48 x 0.48 mm

■ Display Mode: Passive Matrix

■ Display Color: Monochrome (White)

■ Drive Duty: 1/64 Duty

■ Interface: 8-bits 6800 and 8080 parallel, 4-line SPI, I2C

■ IC: SSD1357

■ Size: 2.7 inch



2.Module Classification information

1	2	3	4	5	6	7	8	9	10	11	12	13	14
R	Е	Х	012864	C	W	Р	Р	3	N	0	0	0	00

1	Brand : Raystar Optronics Inc.								
2	E: OLED	E: OLED							
3	Display Type	C: COB Character X: COG P: COG + FR + PCB A: COG + PCB		_	OB Graphic OG + FR .B				
4	Dot Matrix: 1	28*64							
5	Series								
6	Emitting Color	A: Amber B: Blue G: Green S: Sky Blue	R: Red W: White Y: Yellow X: Dual Color		C : Full Color				
7	Polarizer		P : With Polarizer; N: Without Polarizer A : Anti-glare Polarizer						
8	Display Mode	P : Passive Matri	P : Passive Matrix ; N : Active Matrix						
9	Driver Voltage		3:3.0~3.3V; 5:5.0V						
10	Touch Panel	N: Without touch	panel; T: With tou	ch pane					
11	Product type	0 : Standard 1 : Daylight Read 2 : Transparent C 3 : Flexible OLED 4 : OLED Lighting	LED (TOLED) (FOLED)						
12	Inspection Gra	Y : Consumer gra							
13	Option								
14	Serial No. Serial number(00~ZZ)								



3.Interface Pin Function

No.	Symbol	Function
1	NC(GND)	No connection.
2	VSS	Ground of Logic Circuit. This is a ground pin. It also acts as a reference for the logic pins. It must be connected to external ground.
3	VCC	Power supply for panel driving voltage. This is also the most positive power voltage supply pin.
4	VCOMH	Voltage Output High Level for COM Signal. This pin is the input pin for the voltage output high level for COM signals. A tantalum capacitor should be connected between this pin and VSS.
5	VLSS	Ground of Analog Circuit These are the analog ground pins. They should be connected to VSS externally.
6~13	D7~D0	These pins are bi-directional data bus connecting to the MCU data bus. Unused pins are recommended to tie LOW. When serial interface mode is selected, D0 will be the serial clock input: SCLK; D1 will be the serial data input: SDIN and D2 should be kept NC. When I2C mode is selected, D2, D1 should be tied together and serve as SDAout, SDAin in application and D0 is the serial clock input, SCL.
14	E/RD#	This pin is MCU interface input. When 6800 interface mode is selected, this pin will be used as the Enable (E) signal. Read/write operation is initiated when this pin is pulled HIGH and the chip is selected. When 8080 interface mode is selected, this pin receives the Read (RD#) signal. Read operation is initiated when this pin is pulled LOW and the chip is selected. When serial or I2C interface is selected, this pin must be connected to VSS.
15	R/W#	This pin is read / write control input pin connecting to the MCU interface. When 6800 interface mode is selected, this pin will be used as Read/Write (R/W#) selection input. Read mode will be carried out when this pin is pulled HIGH and write mode when LOW. When 8080 interface mode is selected, this pin will be the Write (WR#) input. Data write operation is initiated when this pin is pulled LOW and the chip is selected. When serial or I2C interface is selected, this pin must be connected to VSS.



		Communicating Protoco	ol Select.						
		These pins are MCU in	terface selection in	put. See the following table:					
16	BS1		BS1	BS2					
17	BS2	I2C	1	0					
''	632	4-wire Serial	0	0					
		8-bit 8080 Parallel	1	1					
		8-bit 6800 Parallel 0 1							
18	D/C#	data. When the pin is pulled command register. In I2C mode, this pin active When 3-wire serial inte	HIGH, the data at D LOW, the data at D cts as SA0 for slave	D[7:0] will be interpreted as					
19	CS#	Chip Select This pin is the chip select communication only when CS# is pulled low		s enabled for MCU					
20	RES#	This pin is reset signal When the pin is pulled Keep this pin pull HIGH	LÓW, initialization (•					
21	FR	Frame Frequency Trigg This pin will send out a status. Nothing should be conr individually.	signal that could be	e used to identify the driver should be left open					
22	IREF	This pin is the segment IREF is supplied extern	•	erence pin.					
23	N.C.	Reserved Pin The N.C. pin between f flexible design.	unction pins is rese	erved for compatible and					
24	VDD	Power Supply for I/O Pin. This pin is a power supply pin of I/O buffer. It should be connected to VCI or external source. All I/O signal should have VIH reference to VDDIO. When I/O signal pins (BS0~BS1, D0~D7, control signals) pull high, they should be connected to VDDIO.							
25	VP	range of 2.4~2.6V) or rebe connected between	v pin. It can be suppegulated internally this pin & VSS und	blied externally (within the from VCI. A capacitor should er all circumstances.					
26	VDD	Power Supply for Opera This is a voltage supply always be equal to or h	pin. It must be cor	nnected to external source & /DDIO.					

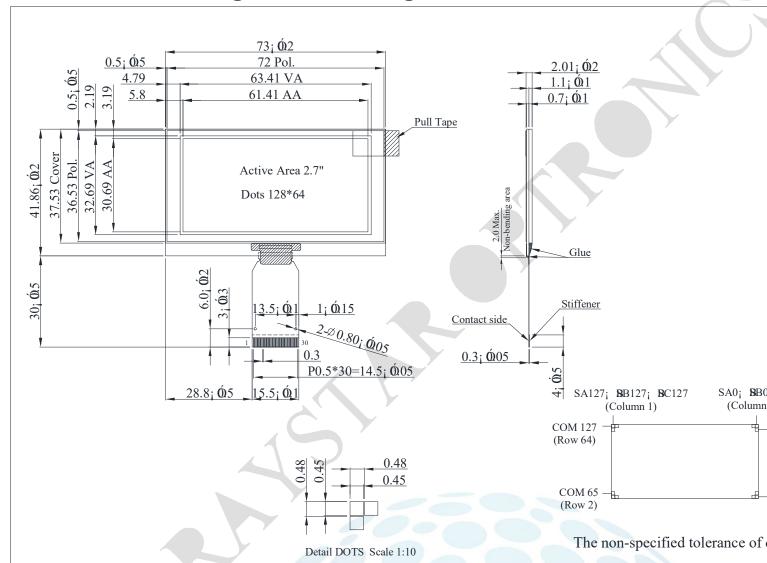


27		Voltage Output Low Level for SEG Signal This is segment voltage reference pin. When external VSL is not used, this pin should be left open. When external VSL is used, this pin should connect with resistor and diode to ground.
28	VLSS	Ground of Analog Circuit These are the analog ground pins. They should be connected to VSS externally.
29	VCC	Power Supply for OEL Panel These are the most positive voltage supply pin of the chip. They must be connected to external source.
30	NC(GND)	No connection



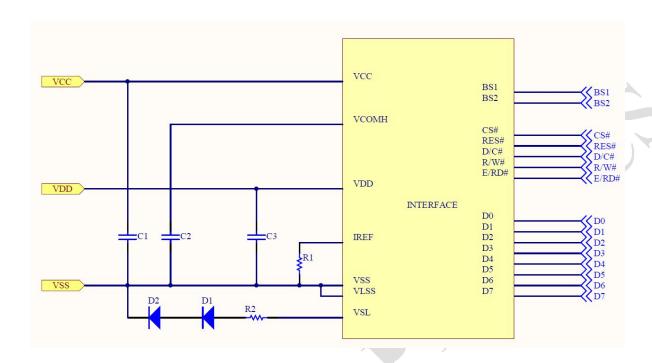


4. Contour Drawing & Block Diagram





4.1 Application recommendations



Recommended components:

C1, C2: 2.2uF/25V/0603 C3: 1.0uF/16V/0603

R2: 20 ohm D1,D2: 1N4148

Bus Interface selection: (Must be set the BS[2:1], refer to item 3)

8-bits 6800 and 8080 parallel, 4-line SPI, I2C

Voltage at IREF = VCC - 2V. For VCC = 10V, IREF = 10uA:

R1 = (Voltage at IREF - VSS) / IREF

= (10-2) / 10u

≅ 800K ohm

Note:

The values are recommended value for 7. Optical Characteristics. Select appropriate value against module application.



5.Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit	Notes
Supply Voltage for Logic	VDD	-0.3	4.0	V	1,2
Supply Voltage for Display	VCC	0	15.0	V	1,2
Operating Temperature	TOP	-40	+80	°C	-
Storage Temperature	TSTG	-40	+85	°Ć	

Note 1: All the above voltages are on the basis of "VSS = 0V".

Note 2: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to Section 6."Optics & Electrical Characteristics". If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate.

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6.Electrical Characteristics

6.1 DC Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage for Logic	VDD	_	2.8	3.0	3.3	V
Supply Voltage for Display	VCC	_	9.5	10.0	10.5	V
High Level Input	VIH	_	0.8×VDD	-/		V
Low Level Input	VIL	_	_	-	0.2×VDD	V
High Level Output	VOH	_	0.9×VDD		_	٧
Low Level Output	VOL	_			0.1×VDD	٧
50% Check Board operati Current	ng	VCC =10.0V		46	69	mA





6.2 Initial code

}

```
void Initial SSD1357(){
               write command(0xfd);
               write data(0x12);
               write command(0xae);
               write command(0xa0);
               write data(0x12);
                                                 //A[7:6] Set Color Depth,
                                                 //10b: Enable Dual-COM
               write data(0x10);
               write command(0xa1);
               write data(0x00);
               write command(0xa2);
               write data(0x00);
               write command(0xa6);
               write command(0xb1);
               write data(0xFF);
               write command(0xb3);
                                                  //Oscillator Frequency
               write data(0x20);
                                                  //105Hz
               write command(0xb6);
               write data(0x0f);
               write command(0xb9);
               write command(0xbb);
               write data(0x1f);
               write command(0xbe);
                                                 //Set VCOMH
               write data(0x07);
                                                 //0.86*VCC
               write command(0xc1);
                                                 //Contrast Current
                                                 //Blue contrast set
               write data(0xcf);
               write data(0xcf);
                                                 //Green contrast set
                                                 //Red contrast se
               write data(0xcf);
               write command(0xca);
                                                 //Set MUX Ratio
               write data(0x7f);
                                                 //128 Duty
               write command(0xaf);
                                                 //Display on
```



6.3 Application Note for RAM mapping

Data bus to RAM mapping under different input mode

Write	data			-	Data	bus			
Depth	Input order	D7	D6	D5	D4	D3	D2	D1	D0
Mono	-				0xFF	/ 0x00			
16Cray	1st	Χ	Χ	D3	D2	D1	D0	X	X
16Gray Scale	2nd	Χ	Χ	D3	D2	D1	D0	X	X
Scale	3rd	Χ	Χ	D3	D2	D1	D0	X	X

```
Example code
(A) Mono
write_command(0xa0);
write_data(0x12); //A[7:6] Set Color Depth,
//00b: mono
```

```
//10b: 16 Gray Scale
write_data(0x10); //0x10: Enable Dual-COM; 0x00: Disable
```

```
write_command(0x15); //Column
write_data(0x00);
write_data(0x7F);
```

```
write_command(0x75); //Row write_data(0x00);
```

(B)16 Gray Scale

```
write_command(0xA0);
write_data(0x92); //A[7:6] Set Color Depth,
```

write_data(0x92), //A[7:6] Set Color De| //00b: mono

//10b: 16 Graycale write data(0x10); //0x10: Enable Dual-COM; 0x00 : Disable

write command(0x15); //Column

write_data(0x00);

write_data(0x7F); write_command(0x75); //Row

write_data(0x00);

write_data(0x3F);
write_command(0x56)

write_command(0x5C);
for(y=0x00;y<0x40;y++)</pre>

{ for(x=0;x<64;x=x+4) //16 G.S.

write_data(x);
} }

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6.4 Command Table

(D/C# = 0, R/W#(WR#) = 0, E(RD#) = 1) unless specific setting is stated Single byte command (D/C# = 0), Multiple byte command (D/C# = 0) for first byte, D/C# = 1 for other bytes)

	mental (,,		•		ic communa (i	Bron o for mot byte, Bron 1 for other bytesy
D/C#	Hex	D7	D 6	D5	D4	D3	D2	D1	D 0	Command	Description
0 1 1	15 A[6:0] B[6:0]	0 *	0 A ₆ B ₆	100.00	1 A ₄ B ₄	0 A ₃ B ₃	1 A ₂ B ₂		1 A ₀ B ₀	Set Column Address	A[6:0]: Start Address. [reset=0] B[6:0]: End Address. [reset=127] Range from 0 to 127
0 1 1	75 A[6:0] B[6:0]	0 *	1 A ₆ B ₆		1 A ₄ B ₄	0 A ₃ B ₃	1 A ₂ B ₂	0 A ₁ B ₁	1 A ₀ B ₀	Set Row Address	A[6:0]: Start Address. [reset=0] B[6:0]: End Address. [reset=127] Range from 0 to 127
0	5C 5D	0	1	0	1	1	1	0	1	Write RAM Command Read RAM Command	Enable MCU to write Data into RAM Enable MCU to read Data from RAM
0 1 1	A0 A[7:0] B[7:0]	1 A ₇ 0	0 A ₆ 0	1 A ₅ 0	0 A ₄ 0	0 A ₃ 0	0 A ₂ 0	0 A ₁ 0	0 A ₀ 0	Set Re-map / Color Depth (Display RAM to Panel)	 A[0]=0b, Horizontal address increment [reset] A[0]=1b, Vertical address increment A[1]=0b, Column address 0 is mapped to SEG0 [reset] A[1]=1b, Column address 127 is mapped to SEG0 A[2]=0b, Color sequence: A → B → C [reset] A[2]=1b, Color sequence is swapped: C → B → A A[3]=0b, Reserved [reset] A[3]=1b, Reserved A[4]=0b, Scan from COM0 to COM[N-1] [reset] A[4]=1b, Scan from COM[N-1] to COM0. Where N is the Multiplex ratio. A[5]=0b, Disable COM Split Odd Even A[5]=1b, Enable COM Split Odd Even [reset] A[7:6] Set Color Depth, 00b: 256color 01b: 262k color 11b Pseudo 262k color, 16-bit format 2 Refer to Product Preview Table 6-6 for details



Funda	mental (Com	man	d Ta	ble						
D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	A1 A[6:0]	1 *	0 A ₆	1 A ₅	0 A ₄	0 A ₃	0 A ₂	0 A ₁	1 A ₀	Set Display Start Line	Set vertical scroll by RAM from 0~127. [reset=00h]
0	A2 A[6:0]	1 *	0 A ₆	1 A ₅	0 A ₄	0 A ₃	0 A ₂	1 A ₁	0 A ₀	Set Display Offset	Set vertical scroll by Row from 0-127. [reset=00h]
0	A4~A7	1	0	1	0	0	1	X ₁	X ₀	Set Display Mode	A4h: All OFF A5h: All ON (All pixels have GS63) A6h: Reset to normal display [reset] A7h: Inverse Display (GS0 -> GS63, GS1 -> GS62,)
0	AE~AF	1	0	1	0	1	1	1	X ₀	Set Sleep mode ON/OFF	AEh = Sleep mode On (Display OFF) AFh = Sleep mode OFF (Display ON)
0 1	B1 A[7:0]	1 A ₇	0 A ₆	1 As	1 A ₄	0 A ₃	0 A ₂	0 A ₁	1 A ₀	Set Reset (Phase 1) / Pre-charge (Phase 2) period	A[3:0] Phase 1 period of 2~30 DCLK(s) clocks [reset=0100b] A[3:0]: 0 invalid 1 = 2 DCLKs 2 = 4 DCLKs : 15 = 30DCLKs A[7:4] Phase 2 period of 2~30 DCLK(s) clocks [reset=1000b] A[7:4]: 0 invalid 1 = 2 DCLKs 2 = 4 DCLKs : 15 = 30DCLKs Note (1) 0 DCLK is invalid in phase 1 & phase 2



Funda	mental (om	man	a ra	ble						
D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
						0 A ₃	0 A ₂	1 A ₁	1 A ₀	Front Clock Divider (DivSet)/ Oscillator Frequency	Description
0 1	B6 A[3:0]	1 0	0 0	1 0	1 0	0 A ₃	1 A ₂	0 A ₁	0 A ₀	Set Second Pre- charge Period	A[3:0] Set Second Pre-charge Period 0000b invalid 0001b 1 DCLKS 0010b 2 DCLKS 1000 8 DCLKS [reset] 1111 15 DCLKS
0 1 1 1 1 1 1 1		A2 ₇	A2 ₆		A2 ₄	A2 ₃	A2 ₂	A2 ₁	A2 ₀	Master Look Up Table for Gray Scale Pulse width	The next 63 data bytes define Gray Scale (GS) Table by setting the gray scale pulse width in unit of DCLK's (ranges from 0d ~ 180d). A1[7:0]: Gamma Setting for GS1, A2[7:0]: Gamma Setting for GS2, : A62[7:0]: Gamma Setting for GS62, A63[7:0]: Gamma Setting for GS63 Note (1] 0 \leq Setting of GS1 < Setting of GS2 < Setting of GS3 <p>Setting of GS62 < Setting of GS63</p> (2) GS0 does not has pre-charge and current drive stages. (3) GS1 can be set as only pre-charge but no current drive stage by input gamma setting for GS1 equals 0. (4) When command B8h is input only, color A, B, C will follow the master LUT. (5) When command BCh is input, it selects individual LUT for color A, GS1~31A; When command BDh is input, it selects individual LUT for color C, GS1~31C (6) To select individual LUT for color B, A and C, command B8h should be input before command BCh and BDh,



D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	$\mathbf{D0}$	Command	Description
0		1		1		1		0	20.0	Command	Reset to default Look Up Table:
U	B9	1	0	1	1	1	0	U	1		Reset to default book op Table.
											Color A Color B Color C
										Use Built-in	GS1A = 0 DCLK GS1B = 0 DCLK GS1C = 0 DCLK
										Linear LUT	GS2A = 4 DCLK
										[reset= linear]	
										1	GS31A = 120 DCLK GS62B = 122 DCLK GS31C = 120 DCLK
											GS63B = 124 DCLK
0	BB	1	0	1	1	1	0	1	1		Set pre-charge voltage level.[reset = 11110b]
1	A[4:0]	0	0	0	A_4	A_3	A_2	A_1	A_0		
											A[4:0] Hex code pre-charge voltage
											$00000 00h 0.10 \text{ x V}_{CC}$
										C - 4 D 1	: : :
										Set Pre-charge voltage	11110 1Eh 0.50 x V _{CC} [reset]
										voltage	11111 1Fh $0.5133 \times V_{CC}$
											Note
											(1)Pre-charge voltage level must be smaller than COM
											deselect voltage level
											descreet voltage level
0	BC	1	0	1	1	1	1	0	0		The next 31 data bytes define Gray Scale (GS) Table by
1	A1[7:0]	A1 ₇	A1.	A1.	A14	A12	A12	A1,	A 10		setting the gray scale pulse width in unit of DCLK's
		A27									(ranges from $0d \sim 180d$) for color A.
1	A2[7.0]	A27	A26	A25	A24	A23	A22	A21	A20		
1									15		A1[7:0]: Gamma Setting for GS1A,
1											A2[7:0]: Gamma Setting for GS2A,
1											:
1	A30[7:0]	A30 ₇	A30 ₆	A30 ₅	A30 ₄	A30 ₃	A30 ₂	A30 ₁	A30 ₀		A62[7:0]: Gamma Setting for GS30A,
1	A31[7:0]									Individual Look	A63[7:0]: Gamma Setting for GS31A
1	A31[7.0]	1317	71.0	71315	1314	1313	A312	ASI	A310	Up Table for	
										Gray Scale	Note
										Pulse width	(1) 0 \leq Setting of GS1 \leq Setting of GS2
										(Color A)	< Setting of GS30 < Setting of GS31
											(2) GS0 does not has pre-charge and current drive stages.
											(3) GS1 can be set as only pre-charge but no current drive
											stage by input gamma setting for GS1 equals 0.
											(4) When command B8h is input, it selects one LUT for col
											A, B and C. i.e. GS1~31A, GS1~63B and GS1~31C are
											updated. (5) Command BSh should be imput before command BCh as
											(5) Command B8h should be input before command BCh at BDh to select individual LUT for color B, A and C.
											DDII to select individual LOT for color B, A and C.



	Indamental Command Table												
D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D 0	Command	Description		
0 1 1 1 1 1 1	A2[7:0]	A27	A26	A25	A24	A30 ₃	A2 ₂	A2 ₁	A2 ₀		The next 31 data bytes define Gray Scale (GS) Table by setting the gray scale pulse width in unit of DCLK's (ranges from 0d ~ 180d) for color C. A1[7:0]: Gamma Setting for GS1C, A2[7:0]: Gamma Setting for GS2C, : A62[7:0]: Gamma Setting for GS30C, A63[7:0]: Gamma Setting for GS31C Note (1] 0 ≤ Setting of GS1 < Setting of GS2 < Setting of GS3 < Setting of GS30 < Setting of GS31 (2) GS0 does not has pre-charge and current drive stages. (3) GS1 can be set as only pre-charge but no current drive stage by input gamma setting for GS1 equals 0. (4) When command B8h is input, it selects one LUT for color A, B and C. i.e. GS1~31A, GS1~63B and GS1~31C are updated. (5) Command B8h should be input before command BCh and BDh to select individual LUT for color B, A and C.		
0	BE A[2:0]	1 0	0 0	1 0	1 0	1 0	1 A ₂	1 A ₁	0 A ₀	Set V _{COMH} Voltage	A[2:0] Hex code V _{COMH} 000 00h 0.72 x V _{CC} : : : : : 101 05h 0.82 x V _{CC} [reset] : : : : : : 111 07h 0.86 x V _{CC}		
0 1 1 1	C1 A[7:0] B[7:0] C[7:0]	1 A ₇ B ₇ C ₇	1 A ₆ B ₆ C ₆	0 A ₅ B ₅ C ₅	0 A ₄ B ₄ C ₄	0 A ₃ B ₃ C ₃	0 A ₂ B ₂ C ₂	0 A ₁ B ₁ C ₁	1 A ₀ B ₀ C ₀	Set Contrast Current for Color A,B,C	A[7:0] Contrast Value Color A [reset=7Fh] B[7:0] Contrast Value Color B [reset=7Fh] C[7:0] Contrast Value Color C [reset=7Fh]		
0 1	C7 A[3:0]	1 *	1 *	0 *	0 *	0 A ₃	1 A ₂	1 A ₁	1 A ₀	Master Contrast Current Control			
0	CA A[6:0]	1 0	1 A ₆	0 A ₅	0 A ₄	1 A ₃	0 A ₂	1 A ₁	0 A ₀	Set MUX Ratio	A[6:0] MUX ratio 4MUX ~ 128MUX, [reset=127], (Rang from 3 to 127)		
0	E3	1	1	1	0	0	0	1	1	NOP	Command for No Operation		



Funda	Fundamental Command Table										
D/C#	Hex	D7	D 6	D5	D4	D3	D2	D1	D 0	Command	Description
0	FD	1	1	1	1	1	1	0	1		A[7:0]: MCU protection status [reset = 12h]
1	A[7:0]	A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀	Set Command Lock	A[7:0] = 12h, Unlock OLED driver IC MCU interface from entering command [reset] A[7:0] = 16h, Lock OLED driver IC MCU interface from entering command
											Note (1) The locked OLED driver IC MCU interface prohibits all commands and memory access except the FDh command.

Note
(1) "*" stands for "Don't care".



Graphic Acceleration Command List

Set (GAC) (D/C# = 0, R/W#(WR#)= 0, E(RD#) = 1) unless specific setting is stated Single byte command (D/C# = 0), Multiple byte command (D/C# = 0 for first byte, D/C# = 1 for other bytes)

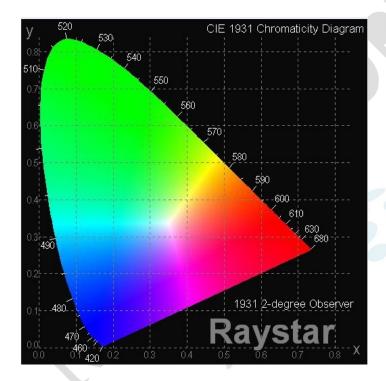
11 CC4
1 column offset
column offset
the scrolling
ritten

Note
(2) "*" stands for "Don't care".



7. Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Viou Anglo	(V)θ	_	160	_	-	deg
View Angle	(Η)φ	_	160	_	70	deg
Contrast Ratio	CR	Dark	2000:1	_	(-	/ _
Deepers Time	T rise	_	_	10		μs
Response Time	T fall	_	_	10	X	μs
Display with 50% che	ck Board Brigh	itness	60	80	_	cd/m2
CIEx(Wh	ite)	(CIE1931)	0.24	0.28	0.32	_
CIEy(Wh	ite)	(CIE1931)	0.28	0.32	0.36	_







8.OLED Lifetime

ITEM	Conditions	Min	Тур	Remark
Operating Life Time	Ta=25°C / Initial 50% check board brightness Typical Value	20,000 Hrs	-	Note

Notes:

- 1. Life time is defined the amount of time when the luminance has decayed to <50% of the initial value.
- 2. This analysis method uses life data obtained under accelerated conditions to extrapolate an estimated probability density function (*pdf*) for the product under normal use conditions.
- 3. Screen saving mode will extend OLED lifetime.





9.Reliability

Content of Reliability Test

Environmenta	1		Applicable
Test Item	Content of Test	Test Condition	Standard
High Temperature storage	Endurance test applying the high storage temperature for a long time.	85°C 240hrs	- (
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-40°C 240hrs	-
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	80°C 240hrs	
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-40°C 240hrs	
High Temperature/ Humidity Storage	Endurance test applying the high temperature and high humidity storage for a long time.	60°C,90%RH 240hrs	
High Temperature/ Humidity Operation	Endurance test applying the high temperature and high humidity Operation for a long time.	60°C,90%RH 120hrs	
Temperature Cycle	Endurance test applying the low and high temperature cycle. -40°C 25°C 80°C 30min 5min 30min 1 cycle	-40°C /80°C 30 cycles	257
Mechanical Tes	st		
Vibration test	Endurance test applying the vibration during transportation and using.	Frequency:10~55Hz amplitude:1.5mm Time:0.5hrs/axis Test axis:X,Y,Z	
Others			
Static electricity test	Endurance test applying the electric stress to the finished product housing.	Air Discharge model ±4kv,10 times	_

^{***} Supply voltage for OLED system =Operating voltage at 25°C



Test and measurement conditions

- 1. All measurements shall not be started until the specimens attain to temperature stability. After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure test at 23±5°C; 55±15% RH.
- 2. All-pixels-on is used as operation test pattern.
- 3. The degradation of Polarizer are ignored for High Temperature storage, High Temperature/ Humidity Storage, Temperature Cycle

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Evaluation criteria

- 1. The function test is OK.
- 2. No observable defects.
- 3. Luminance: > 50% of initial value.
- 4. Current consumption: within ± 50% of initial value.

APPENDIX:

RESIDUE IMAGE

Because the pixels are lighted in different time, the luminance of active pixels may reduce or differ from inactive pixels. Therefore, the residue image will occur. To avoid the residue image, every pixel needs to be lighted up uniformly.



10.Inspection specification

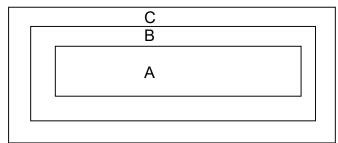
Inspection Standard:

MIL-STD-105E table normal inspection single sample level II.

Definition

- 1 Major defect: The defect that greatly affect the usability of product.
- 2 Minor defect: The other defects, such as cosmetic defects, etc.

Definition of inspection zone:



Zone A: Active Area

Zone B: Viewing Area except Zone A

Zone C: Outside Viewing Area

Note: As a general rule, visual defects in Zone C are permissible, when it is no trouble of quality and assembly to customer's product.

Inspection Methods

- 1 The general inspection : Under fluorescent light illumination: 750~1500 Lux, about 30cm viewing distance, within 45° viewing angle, under 25±5°C.
- 2 The luminance and color coordinate inspection : By SR-3 or BM-7 or the equal equipments, in the dark room, under 25±5°C.

NO	Item	Criterion	AQL
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 OLED viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect. 	0.65
02	Black or white spots on OLED (display only)	2.1 White and black spots on display • 0.25mm, no more than three white or black spots present.2.2 Densely spaced: No more than two spots or lines within 3mm.	2.5



NO	Item		Criterior	า		AQL	
	OLED black spots, white spots, contamin ation (non-display)	3.1 Round type : As following drawing $\Phi=(x+y)/2$ $X = \frac{1}{4}$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi$					
03		→ L <u>w</u>	11 = 0.02 7 (0.05)				
		L≦3. L≦2.:			A+B A+B		
			/ =				
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.	Size Φ $\Phi \le 0.20$ $0.20 < \Phi \le 0.50$ $0.50 < \Phi \le 1.00$ $1.00 < \Phi$ Total Q TY	Acceptable Q TY Accept no dense 3 2 0 3	Zone A+B A+B A+B A+B	2.5	
05	Scratches	Follow NO.3 OLED) black spots, white	e spots, contaminati	on.		



NO	Item	Criterion	AQL
	Chipped glass	Symbols Define: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: OLED side length L: Electrode pad length: 6.1 General glass chip: 6.1.1 Chip on panel surface and crack between panels:	2.5
06	giaco	6.1.2 Corner crack: $ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	2.5
	Glass crack	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	2.5



NO	Item	Criterion	
06	Glass crack	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	2.5
07	Cracked glass	The OLED with extensive crack is not acceptable.	
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using OLED spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 	
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination. 9.2 Bezel must comply with job specifications.	



NO	Item	Criterion	AQL
10	PCB , COB	10.1 COB seal may not have pinholes larger than 0.2mm or contamination.	2.5
		10.2 COB seal surface may not have pinholes through to the IC.10.3 The height of the COB should not exceed the height indicated in the assembly diagram.	2.5 0.65
		10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places.	2.5
		10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts.	2.5 0.65
		10.7 The jumper on the PCB should conform to the product characteristic chart.	0.65
		10.8 If solder gets on bezel tab pads, OLED pad, zebra pad or screw hold pad, make sure it is smoothed down.	2.5
11	Soldering	11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation	2.5 2.5
		or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB.	2.5 0.65
12	General	12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.	2.5
		12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on	0.65 2.5
		product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever.	2.5 2.5
		12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color.	2.5
		12.7 Sealant on top of the ITO circuit has not hardened. 12.8 Pin type must match type in specification sheet.	2.5 0.65
		12.9 OLED pin loose or missing pins.	0.65
		12.10 Product packaging must the same as specified on packaging specification sheet.	0.65
		12.11 Product dimension and structure must conform to product specification sheet.	0.65



Check Item	Classification	Criteria
No Display	Major	
Missing Line	Major	
Pixel Short	Major	
Darker Short	Major	
Wrong Display	Major	
Un-uniform B/A x 100% < 70% A/C x 100% < 70%	Major	A Normal B Dark Pixel C Light Pixel



11. Precautions in use of OLED Modules

- (1) Avoid applying excessive shocks to module or making any alterations or modifications to it.
- (2) Don't make extra holes on the printed circuit board, change the components or modify its shape of OLED display module.
- (3) Don't disassemble the OLED display module.
- (4) Do not apply input signals while the logic power is off.
- (5) Don't operate it above the absolute maximum rating.
- (6) Don't drop, bend or twist OLED display module.
- (7) Soldering: only to the I/O terminals.
- (8) Hot-Bar FPC soldering condition: 280~350C, less than 5 seconds.
- (9) Raystar has the right to change the passive components (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.) and change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Raystar have the right to modify the version.)
- (10) Raystar has the right to upgrade or modify the product function.

11.1. Handling Precautions

- (1) Since the display panel is being made of glass, do not apply mechanical impacts such as dropping from a high position.
- (2) If the display panel is broken by some accident and the internal organic substance leaks out, be careful not to inhale nor lick the organic substance.
- (3) If pressure is applied to the display surface or its neighborhood of the OLED display module, the cell structure may be damaged. So, be careful not to apply pressure to these sections.
- (4) The polarizer covering the surface of the OLED display module is soft and easily scratched.
- (5) When the surface of the polarizer of the OLED display module has soil, clean the surface. It takes advantage by using following adhesion tape.
 - * Scotch Mending Tape No. 810 or an equivalent

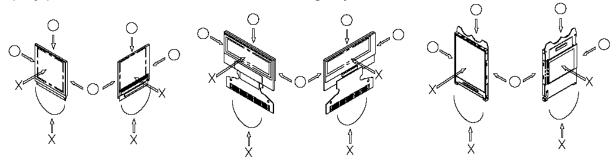
Never try to breathe upon the soiled surface nor wipe the surface using cloth containing solvent such as ethyl alcohol, since the surface of the polarizer will become cloudy.

Also, pay attention that the following liquid and solvent may spoil the polarizer:

- * Water
- * Ketone
- * Aromatic Solvents
- (6) Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. At this time, if the OLED display module has been stored for a long period of time, residue adhesive material of the protection film may remain on the surface of the display panel after removed of the film. In such case, remove the residue material by the method introduced in the above Section 5.
- (7) Do not touch the following sections whenever possible while handling the OLED display modules.
 - * Pins and electrodes
 - * Pattern layouts such as the TCP & FPC
- (8) Hold OLED display module very carefully when placing OLED display module into the



System housing. Do not apply excessive stress or pressure to OLED display module. And, do not over bend the film with electrode pattern layouts. These stresses will influence the display performance. Also, secure sufficient rigidity for the outer cases.



- (9) Do not apply stress to the LSI chips and the surrounding molded sections.
- (10) Pay sufficient attention to the working environments when handing OLED display modules to prevent occurrence of element breakage accidents by static electricity.
 - * Be sure to make human body grounding when handling OLED display modules.
 - * Be sure to ground tools to use or assembly such as soldering irons.
 - * To suppress generation of static electricity, avoid carrying out assembly work under dry environments.
 - * Protective film is being applied to the surface of the display panel of the OLED display module. Be careful since static electricity may be generated when exfoliating the protective film.

11.2. Storage Precautions

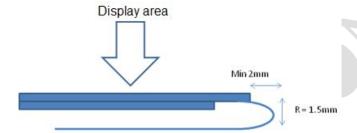
- (1) When storing OLED display modules, put them in static electricity preventive bags to avoid be directly exposed to sun or lights of fluorescent lamps. (We recommend you to store these modules in the packaged state when they were shipped from Raystar. At that time, be careful not to let water drops adhere to the packages or bags.)
- (2) When the OLED display module is being dewed or when it is placed under high temperature or high humidity environments, the electrodes may be corroded if electric current is applied. Please store it in clean environment.

11.3. Designing Precautions

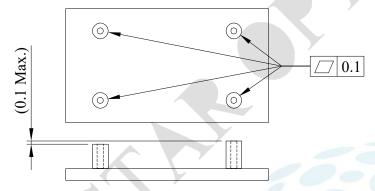
- (1) The absolute maximum ratings are the ratings which cannot be exceeded for OLED display module, and if these values are exceeded, OLED display module may be damaged.
- (2) To prevent occurrence of malfunctioning by noise, pay attention to satisfy the VIL and VIH specification and to make the signal line cable as short as possible.
- (3) We recommend you to install excess current preventive unit (fuses, etc.) to the power circuit (VDD / VCC). (Recommend value: 0.5A)
- (4) Pay sufficient attention to avoid occurrence of mutual noise interference with the nearby devices.
- (5) As for EMI, take necessary measures on the equipment side basically.
- (6) If the power supplied to the OLED display module is forcibly shut down by such errors as taking out the main battery while the OLED display panel is in operation, we cannot guarantee the quality of this OLED display module.
 - * Connection (contact) to any other potential than the above may lead to rupture of the IC.



- (7) If this OLED driver is exposed to light, malfunctioning may occur and semiconductor elements may change their characteristics.
- (8) The internal status may be changed, if excessive external noise enters into the module. Therefore, it is necessary to take appropriate measures to suppress noise generation or to protect module from influences of noise on the system design.
- (9) We recommend you to make periodical refreshment of the operation statuses (re-setting of the commands and re-transference of the display data) to cope with catastrophic noise.
- (10) It's pretty common to use "Screen Saver" to extend the lifetime and Don't use the same image for long time in real application. When an OLED display module is operated for a long of time with fixed pattern, an afterimage or slight contrast deviation may occur.
- (11) The limitation of FPC and Film bending.



(12) The module should be fixed balanced into the housing, or the module may be twisted.



11.4. Precautions when disposing of the OLED display modules

(1) Request the qualified companies to handle industrial wastes when disposing of the OLED display modules. Or, when burning them, be sure to observe the environmental and hygienic laws and regulations.





Page: 1

Module Sample Estimate Feedback Sheet					
Module Number:					
1 · Panel Specification :					
1. Panel Type:	□ Pass	□NG ,			
2. Numbers of Pixel:	□ Pass	□NG ,			
3. View Area:	□ Pass	□NG ,			
4. Active Area:	□ Pass	□NG ,			
5.Emitting Color:	□ Pass	□NG ,			
6.Uniformity:	□Pass	□NG ,			
7.Operating	□ Pass	□NG ,			
Temperature :		Y Y			
8.Storage Temperature :	□ Pass	□NG ,			
9.Others:	9.Others :				
2 · Mechanical Specification :					
1. PCB Size:	□Pass	□NG ,			
2.Frame Size :	□Pass	□NG ,			
3.Materal of Frame :	□Pass	□NG ,			
4.Connector Position:	□Pass	□NG ,			
5.Fix Hole Position:	□Pass	□NG ,			
6. Thickness of PCB:	□Pass	□NG ,			
7. Height of Frame to	□Pass	□NG ,			
PCB:					
8.Height of Module:	□Pass	□NG ,			
9.Others:	□Pass	□NG ,			
3 · Relative Hole Size :					
1.Pitch of Connector:	□Pass	□NG ,			
2.Hole size of	□Pass	□NG ,			
Connector:					
3.Mounting Hole size:	□Pass	□NG ,			
4.Mounting Hole Type:	□Pass	□NG ,			
5.Others:	□Pass	□NG ,			

>> Go to page 2 <<



		Page: 2				
Module Number :						
4 · Electronic Characteristics of Module :						
1.Input Voltage :	□Pass	□NG ,				
2.Supply Current:	□Pass	□NG ,				
3.Driving Voltage for	□Pass	□NG ,				
OLED:						
4.Contrast for OLED:	□Pass	□NG ,				
5.Negative Voltage	□Pass	□NG ,				
Output:						
6.Interface Function:	□Pass	□NG ,				
7.ESD test:	□Pass	□NG ,				
8.Others: 5 \ Summary:	□Pass	□NG ,				

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